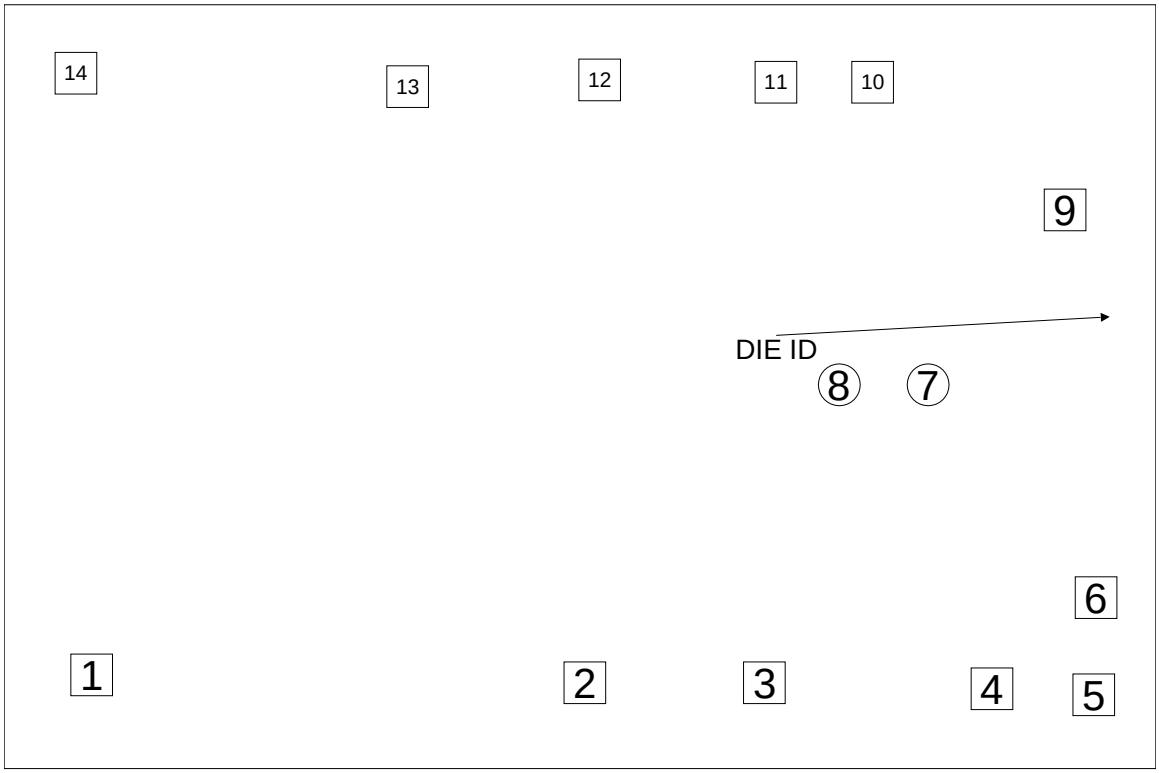
LP2952I-3.3-MDC
ADJUSTABLE MICROPOWER LOW-DROPOUT VOLTAGE REGULATORS

13-Aug-2012

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LP2952B-3.3	Bond Pad Opening Size (min)	89.99µm x 89.99µm
Die Step	B	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	152.4mm	Back Side Metal	BAREBACK
Die Size (Drawn)	2489.2µm x 1651.0µm 98.0mils x 65.0mils	Back Side Connection	Floating or GND
Thickness	304.8µm Nominal		
Min Pitch	381.00µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(B-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
OUTPUT	1	-1055.50	-623.00	90.02	x	89.99
SENSE	2	10.50	-640.00	89.99	x	90.02
$\overline{\text{SHUTDOWN}}$	3	398.50	-640.00	90.02	x	90.02
$\overline{\text{ERROR}}$	4	890.50	-653.00	90.02	x	89.99
NC	5	1110.50	-666.00	89.99	x	89.99
GND	6	1115.50	-455.99	89.99	x	89.99
NC	7	752.50	4.00	90.47	x	90.50
NC	8	560.49	4.00	90.50	x	90.50
NC	9	1048.50	382.00	89.99	x	89.99
NC	10	632.50	658.00	89.99	x	89.99
REF	11	423.51	658.00	89.99	x	89.99
V TAP	12	42.51	663.00	89.99	x	89.99
FEEDBACK	13	-372.50	648.50	89.99	x	89.99
INPUT	14	-1089.49	677.51	89.99	x	89.99

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Notes

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